

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claim 1 (currently amended): A method of assembling a semiconductor device package comprises:

- (i) attaching a semiconductor device to a die-pad area of a leadframe;
- (ii) forming electrical connections between electrical contact areas on the semiconductor device and electrical contact areas on the leadframe to form a device/leadframe assembly;
- (iii) electrolytically depositing an adhesion enhancing coating by an electroplating process on the entire exposed surfaces of the device/leadframe assembly, the enhancing coating being in the form of an inorganic material comprising metal oxide; and
- (iv) encapsulating the coated device/leadframe assembly in an electrically insulating material.

Claim 2 (canceled)

Claim 3 (original): A method according to claim 1, wherein the semiconductor device package is a surface mount semiconductor device package.

Claim 4 (original): A method according to claim 1, further comprising, after encapsulating the coated device/leadframe assembly, removing the coating from non-encapsulated portions of the leadframe.

Claim 5 (currently amended): A semiconductor device package comprises a leadframe; a semiconductor device attached to a first portion of the leadframe; electrical connections extending from electrical contact areas on the semiconductor device to electrical contact areas on a second portion of the leadframe; an adhesion enhancing coating on the entire surfaces of the leadframe, the electrical connections and the semiconductor device; and an electrically insulating material encapsulating the semiconductor device, the electrical connections and the first and second portions of the leadframe, wherein the enhancing coating is in the form of an inorganic material comprising metal oxide.

Claim 6 (canceled).

Claim 7 (currently amended): A semiconductor device package according to claim 6 5, wherein the ~~metallic~~ enhancing coating is an inorganic Zn-CR coating.

Claim 8 (original): A semiconductor device package according to claim 5, wherein the semiconductor device is attached to the first portion of the leadframe by an adhesive.

Claim 9 (original): A semiconductor device package according to claim 5, wherein the semiconductor device is attached to the first portion of the leadframe by solder.

Claim 10 (original): A semiconductor device package according to claim 5, wherein the semiconductor device is a surface mount semiconductor device.

Claim 11 (original): A semiconductor device package according to claim 5, wherein the semiconductor device is a power semiconductor device.

Claim 12 (original): A semiconductor device package according to claim 5, wherein the first portion of the leadframe forms a heat sink for the semiconductor device and a surface of the first portion is not covered by the electrically insulating material.

**Amendments to the Drawings**

Applicants file herewith one (1) sheet of corrected drawings to replace a drawing sheet (1/2) now on file in the above-entitled application. In FIG. 1, the legend "Prior Art" has been added.

Attachment: Replacement Sheet